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ABSTRACT

Encapsulation molding equipment includes individual loading bars each having an elongated support surface which receives strip-like carriers supporting semi-conductor chips and like objects for encapsulation. Cavity inserts having plural rows of cavities of different size and dimension individual to carriers having like numbers of chips of a range of size and dimension fit over the strips with each cavity on an insert surrounding the chip to be encapsulated. Converging gate passages and vent passages are formed on the surface of the insert spaced away from the mold base member for supply of resin from a central resin receptacle to the cavities. Support of the cavity inserts independent of the loading bars and resilient mounting of the loading bars is disclosed. The mold is completed by an upper mold member which closes the mold and effects a seal between the mold parts and provides for delivery of encapsulating resin to the cavities in the cavity inserts. Each mold base has a plurality of recesses, each of which receives a carrier strip and a cavity insert.



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